Most Frequently Occurring Classifications of Patents Returned
From A Search of 10/712,839 on June 10, 2005

Combined Classifications

6	250/208.1
5	257/E21.705
4	257/E27.134
4	428/202
4	428/914
3	250/216
3	257/434
3	257/680
3	257/686
3	257/778
3	257/784
3	257/787
3	257/E31.118
2	29/840
2	29/841
2	156/234
2	156/277
2	250/223R
2	250/226
2	250/548
2	257/432
2	257/433
2	257/666
2	257/678
2	257/704
2	257/723
2	257/737
2	257/777
2	257/E21.511
2	257/E23.033
2	257/E23.041
2	257/E23.052
2	257/E25.011
2	257/E25.013
2	257/E31.128
2	345/50
2	348/87
2	359/565
2	428/207
2	428/211.1
2	428/353
2	428/354
2	438/108
2	438/114
2	438/126
2	438/458
2	438/51

PLUS Search Results for S/N 10712839, Searched June 10, 2005

The Patent Linguistics Utility System (PLUS) is a USPTO automated search system for U.S. Patents from 1971 to the present. PLUS is a query-by-example search system which produces a list of patents that are most closely related linguistically to the application searched. This search was prepared by the staff of the Scientific and Technical Information Center, SIRA.

4987477	6882021	5523608	4454179	5432333
5423119	5225373	5917242	4519234	5519205
5471553	5340420	5981117	4617469	5530278
5862248	5952725	5994166	4759968	5550763
5998862	6134014	6051878	5230458	5576833
6037655	6137570	6080264	5258873	5581632
6399418	4919994	6100108	5274242	5642158
6541284	4999076	6165815	5340978	5648655
6586824	5021676	6245594	5352900	5719440
6734419	5402663	4310978	5407729	5734155

Titles of Most Frequently Occurring Classifications of Patents Returned From A Search of 10/712,839 on June 10, 2005

6 250/208.1 (5 OR, 1 XR)
Class 250 : RADIANT ENERGY
250/200 PHOTOCELLS; CIRCUITS AND APPARATUS
250/206 .Photocell controlled circuit
250/208.1 ..Plural photosensitive image detecting element arrays

4 428/202 (1 OR, 3 XR)
Class 428 : STOCK MATERIAL OR MISCELLANEOUS ARTICLES
428/98 STRUCTURALLY DEFINED WEB OR SHEET (E.G., OVERALL DIMENSION, ETC.)
428/195.1 .Discontinuous or differential coating, impregnation or bond (e.g., artwork, printing, retouched photograph, etc.)
428/201 ..Intermediate layer is discontinuous or differential
428/202 ...With outer strippable or release layer

4 428/914 (0 OR, 4 XR)
Class 428 : STOCK MATERIAL OR MISCELLANEOUS ARTICLES
428/914 TRANSFER OR DECALCOMANIA

3 250/216 (0 OR, 3 XR)
Class 250 : RADIANT ENERGY
250/200 PHOTOCELLS; CIRCUITS AND APPARATUS
250/216 .Optical or pre-photocell system

3 257/434 (1 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/414 RESPONSIVE TO NON-ELECTRICAL SIGNAL (E.G., CHEMICAL, STRESS, LIGHT, OR MAGNETIC FIELD SENSORS)
257/428 .Electromagnetic or particle radiation
257/431 ..Light
257/433 ...With housing or encapsulation
257/434 ....With window means

3 257/680 (2 OR, 1 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/678 HOUSING OR PACKAGE
257/680 .With window means

3 257/686 (1 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/678 HOUSING OR PACKAGE
257/685 .Multiple housings
257/686 ..Stacked arrangement

3 257/778 (0 OR, 3 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
257/778 .Flip chip

3 257/784 (0 OR, 3 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
257/784 .Wire contact, lead, or bond

3 257/787 (0 OR, 3 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/787 ENCAPSULATED

3 257/E31.118 (0 OR, 3 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/E31.046 .....Including microcrystalline Group IV compound (e.g., c-SiGe, c-SiC) (EPO)
257/E31.11 .Detail of nonsemiconductor component of radiation-sensitive semiconductor device (EPO)
257/E31.117 ..Encapsulation (EPO)
257/E31.118 ...For device having potential or surface barrier (EPO)

2 29/840 (0 OR, 2 XR)
Class 029 : METAL WORKING
29/592 METHOD OF MECHANICAL MANUFACTURE
29/592.1 .Electrical device making
29/825 ..Conductor or circuit manufacturing
29/829 ...On flat or curved insulated base, e.g., printed circuit, etc.
29/832 ....Assembling to base an electrical component, e.g., capacitor, etc.
29/840 .....By metal fusion

2 29/841 (1 OR, 1 XR)
Class 029 : METAL WORKING
29/592 METHOD OF MECHANICAL MANUFACTURE
29/592.1 .Electrical device making
29/825 ..Conductor or circuit manufacturing
29/829 ...On flat or curved insulated base, e.g., printed circuit, etc.
29/832 ....Assembling to base an electrical component, e.g., capacitor, etc.
29/841 .....With encapsulating, e.g., potting, etc.

2 156/234 (0 OR, 2 XR)
Class 156 : ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL MANUFACTURE
156/1 METHODS
156/60 .Surface bonding and/or assembly therefor
156/230 ..Direct contact transfer of adhered lamina from carrier to base
156/234 ...Of portion only of lamina from carrier

2 156/277 (0 OR, 2 XR)
Class 156 : ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL MANUFACTURE
156/1 METHODS

156/60 .Surface bonding and/or assembly therefor
156/277 ..With printing

2 250/223R (0 OR, 2 XR)
Class 250 : RADIANT ENERGY
250/200 PHOTOCELLS; CIRCUITS AND APPARATUS
250/216 .Optical or pre-photocell system
250/221 ..Controlled by article, person, or animal
250/222.1 ...Inanimate article
250/223R ....Conveyor or chute

2 250/226 (0 OR, 2 XR)
Class 250 : RADIANT ENERGY
250/200 PHOTOCELLS; CIRCUITS AND APPARATUS
250/216 .Optical or pre-photocell system
250/226 ..Color (e.g., filter or spectroscope)

2 250/548 (2 OR, 0 XR)
Class 250 : RADIANT ENERGY
250/200 PHOTOCELLS; CIRCUITS AND APPARATUS
250/201.1 .Photocell controls its own optical systems
250/548 ..Controlling web, strand, strip, or sheet

2 257/432 (1 OR, 1 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/414 RESPONSIVE TO NON-ELECTRICAL SIGNAL (E.G., CHEMICAL, STRESS, LIGHT, OR MAGNETIC FIELD SENSORS)
257/428 .Electromagnetic or particle radiation
257/431 ..Light
257/432 ...With optical element

2 257/433 (1 OR, 1 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/414 RESPONSIVE TO NON-ELECTRICAL SIGNAL (E.G., CHEMICAL, STRESS, LIGHT, OR MAGNETIC FIELD SENSORS)
257/428 .Electromagnetic or particle radiation
257/431 ..Light
257/433 ...With housing or encapsulation

2 257/666 (0 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/666 LEAD FRAME

2 257/678 (0 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/678 HOUSING OR PACKAGE

2 257/704 (1 OR, 1 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/688 .With large area flexible electrodes in press contact with opposite sides of active semiconductor chip and surrounded by an insulating element, e.g., ring
257/701 .Insulating material
257/704 ..Cap or lid

2 257/723 (0 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/688 .With large area flexible electrodes in press contact with opposite sides of active semiconductor chip and surrounded by an insulating element, e.g., ring
257/723 .For plural devices

2 257/737 (1 OR, 1 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
257/737 .Bump leads

2 257/777 (1 OR, 1 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
257/777 .Chip mounted on chip

2 257/E21.511 (0 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/E21.001 PROCESSES OR APPARATUS ADAPTED FOR MANUFACTURE OR TREATMENT OF SEMICONDUCTOR OR SOLID-STATE DEVICES OR OF PARTS THEREOF (EPO)
257/E21.002 .Manufacture or treatment of semiconductor device (EPO)
257/E21.04 ..Device having at least one potential-jump barrier or surface barrier, e.g., PN junction, depletion layer, carrier concentration layer (EPO)
257/E21.499 ...Assembling semiconductor devices, e.g., packaging , including mounting, encapsulating, or treatment of packaged semiconductor (EPO)
257/E21.506 ....Attaching or detaching leads or other conductive members, to be used for carrying current to or from device in operation (EPO)
257/E21.509 .....Involving soldering or alloying process, e.g., soldering wires (EPO)
257/E21.511 .....Mounting on insulating member provided with metallic leads, e.g., flip-chip mounting, conductive die mounting (EPO)

2 257/E23.033 (0 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
257/E23.01 .Arrangements for conducting electric current to or from solid-state body in operation, e.g., leads, terminal arrangements (EPO)
257/E23.023 ..Consisting of soldered or bonded constructions (EPO)
257/E23.031 ...Lead frames or other flat leads (EPO)
257/E23.032 ....Additional leads (EPO)
257/E23.033 .....Additional leads being bump or wire (EPO)

2 257/E23.041 (0 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
257/E23.01 .Arrangements for conducting electric current to or from solid-state body in operation, e.g., leads, terminal arrangements (EPO)
257/E23.023 ..Consisting of soldered or bonded constructions (EPO)
257/E23.031 ...Lead frames or other flat leads (EPO)
257/E23.041 ....Multilayer (EPO)

2 257/E23.052 (0 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
257/E23.01 .Arrangements for conducting electric current to or from solid-state body in operation, e.g., leads, terminal arrangements (EPO)
257/E23.023 ..Consisting of soldered or bonded constructions (EPO)
257/E23.031 ...Lead frames or other flat leads (EPO)
257/E23.052 ....Assembly of semiconductor devices on lead frame (EPO)

2 257/E25.011 (0 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/E25.001 ASSEMBLIES CONSISTING OF PLURALITY OF INDIVIDUAL SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)

257/E25.002 .All devices being of same type, e.g., assemblies of rectifier diodes (EPO)
257/E25.003 ..Devices not having separate containers (EPO)

257/E25.01 ...Device consisting of plurality of semiconductor or other solid state devices or components formed in or on common substrate, e.g., integrated circuit device (EPO)
257/E25.011 ....Devices being arranged next and on each other, i.e., mixed assemblies (EPO)

2 257/E25.013 (0 OR, 2 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
257/E25.001 ASSEMBLIES CONSISTING OF PLURALITY OF INDIVIDUAL SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)

257/E25.002 .All devices being of same type, e.g., assemblies of rectifier diodes (EPO)
257/E25.003 ..Devices not having separate containers (EPO)

257/E25.01 ...Device consisting of plurality of semiconductor or other solid state devices or components formed in or on common substrate, e.g., integrated circuit device (EPO)
257/E25.013 ....Stacked arrangements of devices (EPO)

2 257/E31.128 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES
257/E31.046 .....Including microcrystalline Group IV compound (e.g., c-SiGe, c-SiC) (EPO)
257/E31.11 .Detail of nonsemiconductor component of radiation-sensitive semiconductor device (EPO)
257/E31.127 ..Optical element associated with device (EPO)

257/E31.128 ...Device having potential or surface barrier (EPO)

2 345/50 (0 OR, 2 XR)
Class 345 : COMPUTER GRAPHICS PROCESSING, OPERATOR INTERFACE PROCESSING, AND SELECTIVE VISUAL DISPLAY SYSTEMS
345/30 PLURAL PHYSICAL DISPLAY ELEMENT CONTROL SYSTEM (E.G., NON-CRT)
345/33 .Segmented display elements
345/48 ..Light-controlling display elements
345/50 ...Liquid crystal elements

2 348/87 (1 OR, 1 XR)
Class 348 : TELEVISION
348/61 SPECIAL APPLICATIONS
348/86 .Manufacturing
348/87 ..Electronic circuit chip or board (e.g., positioning)

2 359/565 (0 OR, 2 XR)
Class 359 : OPTICS: SYSTEMS
359/558 DIFFRACTION
359/565 .From zone plate

2 428/207 (0 OR, 2 XR)
Class 428 : STOCK MATERIAL OR MISCELLANEOUS ARTICLES
428/98 STRUCTURALLY DEFINED WEB OR SHEET (E.G., OVERALL DIMENSION, ETC.)
428/195.1 .Discontinuous or differential coating, impregnation or bond (e.g., artwork, printing, retouched photograph, etc.)
428/206 ..Including particulate material
428/207 ...Including coloring matter

2 428/211.1 (0 OR, 2 XR)
Class 428 : STOCK MATERIAL OR MISCELLANEOUS ARTICLES
428/98 STRUCTURALLY DEFINED WEB OR SHEET (E.G., OVERALL DIMENSION, ETC.)
428/195.1 .Discontinuous or differential coating, impregnation or bond (e.g., artwork, printing, retouched photograph, etc.)
428/211.1 ..Including paper layer

2 428/353 (0 OR, 2 XR)
Class 428 : STOCK MATERIAL OR MISCELLANEOUS ARTICLES
428/221 WEB OR SHEET CONTAINING STRUCTURALLY DEFINED ELEMENT OR COMPONENT

428/343 .Adhesive outermost layer
428/353 ..Including a primer layer

2 428/354 (0 OR, 2 XR)
Class 428 : STOCK MATERIAL OR MISCELLANEOUS ARTICLES
428/221 WEB OR SHEET CONTAINING STRUCTURALLY DEFINED ELEMENT OR COMPONENT
428/343 .Adhesive outermost layer
428/354 ..Three or more layers

2 438/108 (2 OR, 0 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/106 PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING, ETC.) OR TREATMENT OF PACKAGED SEMICONDUCTOR
438/107 .Assembly of plural semiconductive substrates each possessing electrical device
438/108 ..Flip-chip-type assembly

2 438/114 (0 OR, 2 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/106 PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING, ETC.) OR TREATMENT OF PACKAGED SEMICONDUCTOR
438/110 .Making plural separate devices
438/113 ..Substrate dicing
438/114 ...Utilizing a coating to perfect the dicing

2 438/126 (0 OR, 2 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/106 PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING, ETC.) OR TREATMENT OF PACKAGED SEMICONDUCTOR
438/125 .Insulative housing or support
438/126 ..And encapsulating

2 438/458 (0 OR, 2 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/455 BONDING OF PLURAL SEMICONDUCTOR SUBSTRATES
438/458 .Subsequent separation into plural bodies (e.g., delaminating, dicing, etc.)

2 438/51 (2 OR, 0 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/48 MAKING DEVICE OR CIRCUIT RESPONSIVE TO NONELECTRICAL SIGNAL
438/50 .Physical stress responsive
438/51 ..Packaging (e.g., with mounting, encapsulating, etc.) or treatment of packaged semiconductor